
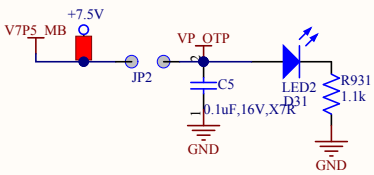
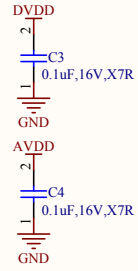
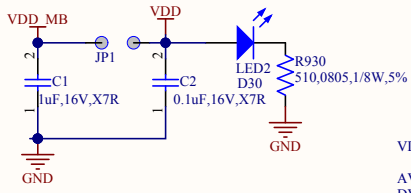


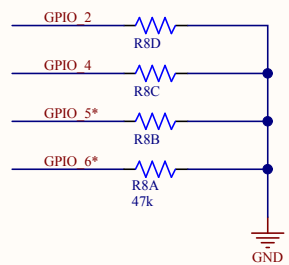
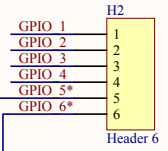
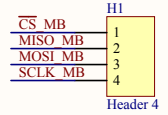
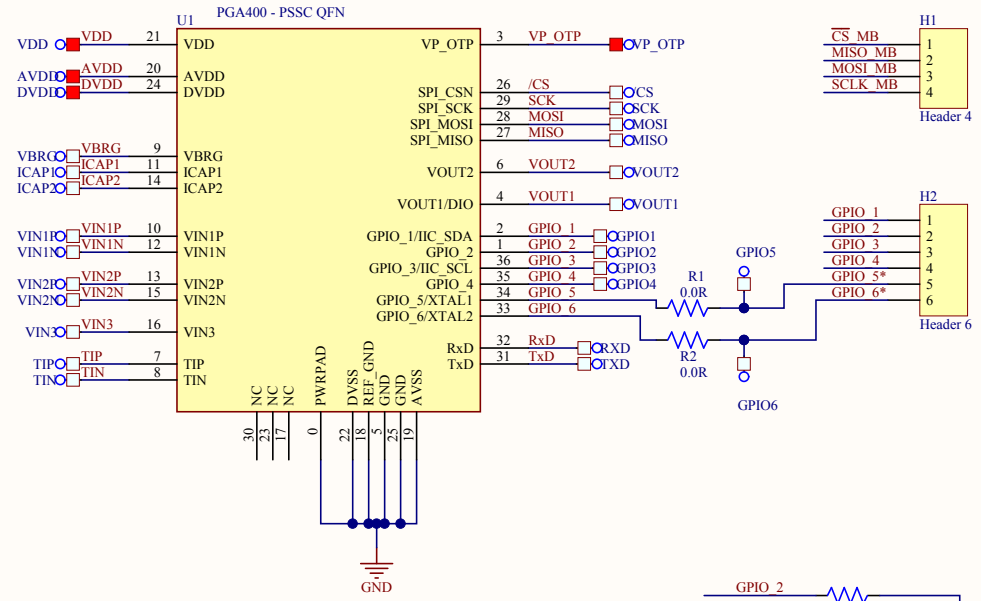
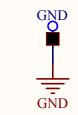
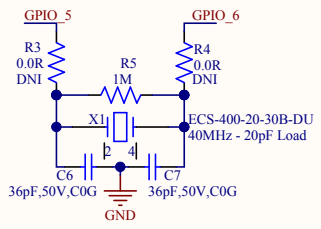
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Number: PRJ Number	Rev: SCH	Designed for: PRJ Customer	Mod. Date: 3/6/2014
SVN Rev: Not in version control	Assembly Variant: Variant name not interpreted	Project Title: PRJ Title	Sheet Title:
Drawn By:	File: Block_Diagram_030614.SchDoc	Sheet: 1 of 1	Size: B
Engineer: PRJ Engineer	Contact: TechSupport	 <a href="http://www.ti.com">http://www.ti.com</a>	

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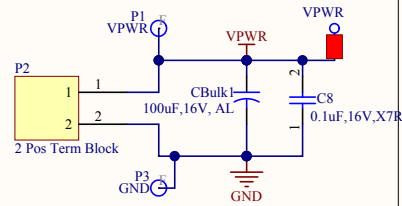


To use XTAL, remove R1 & R2 and install a 0 Ohm resistor or short R3 & R4

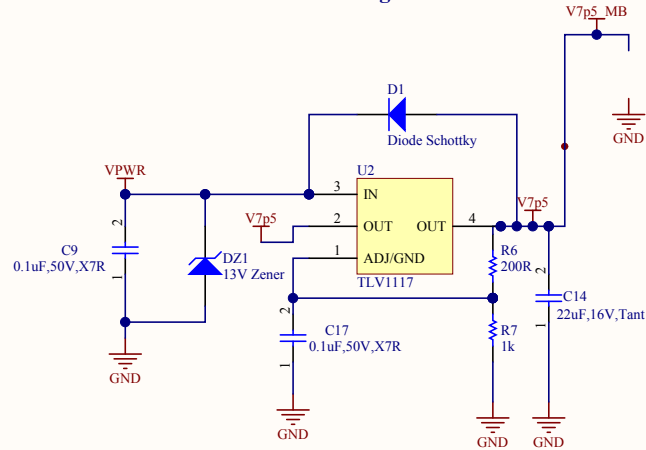


TPIC83R00 - Main

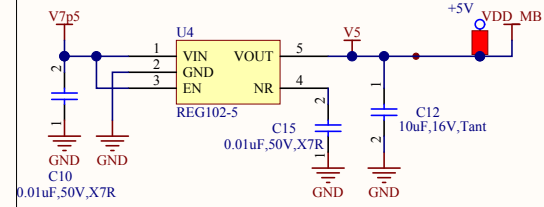
### 9V - 12V Unregulated Input



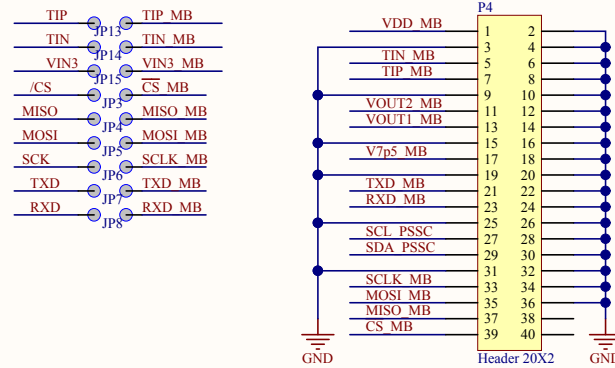
### 7.5V Regulator



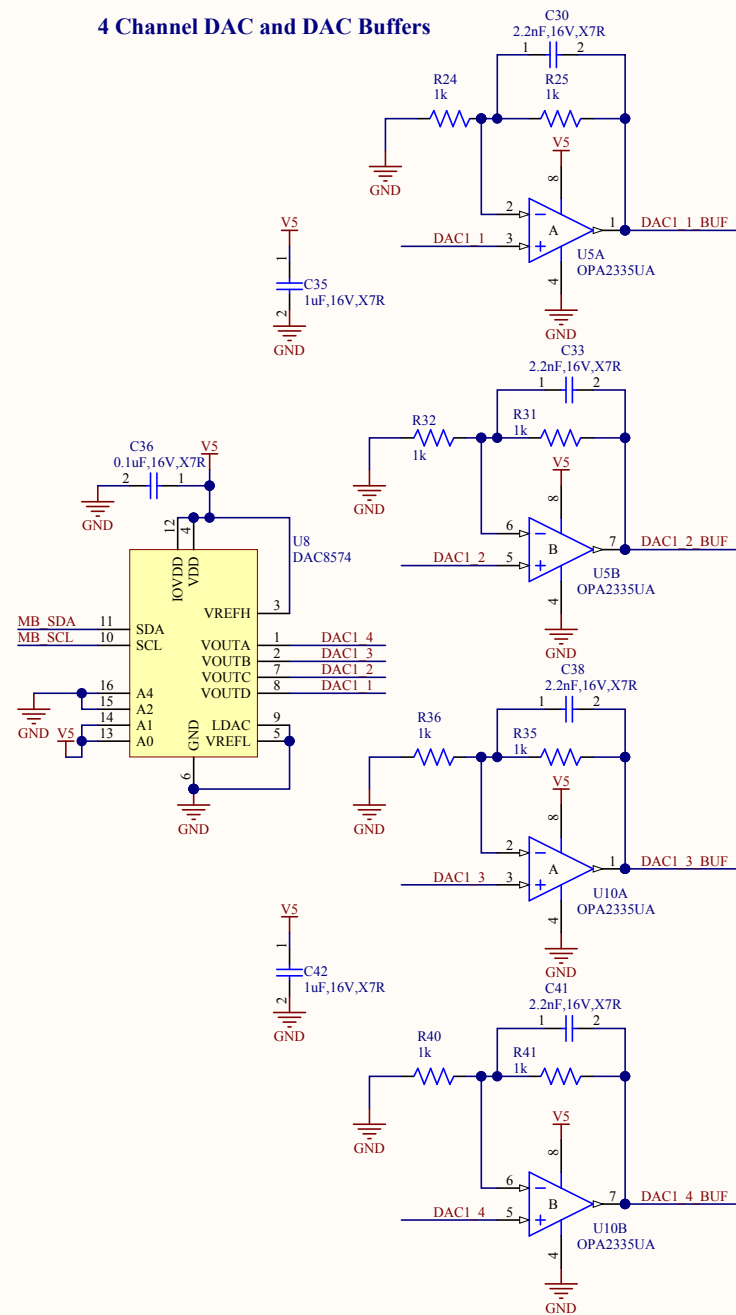
### 5V Regulator



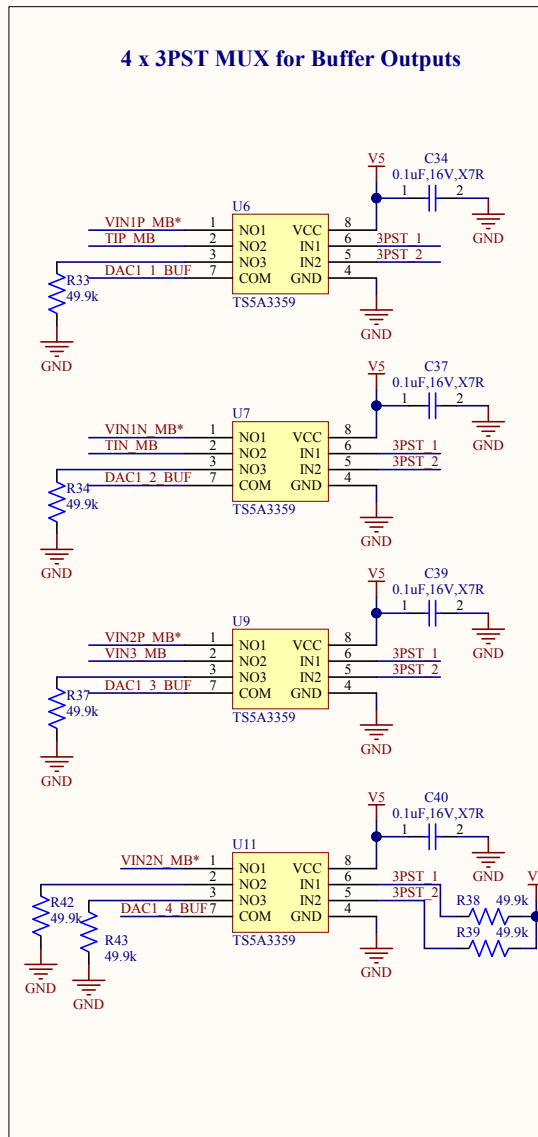
### MotherBoard - DaughterCard Connectors and Jumpers



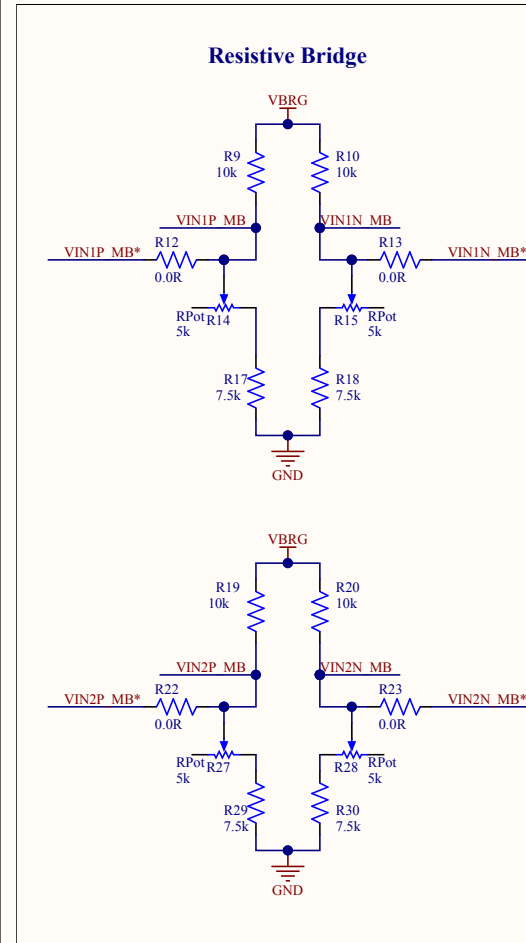
### 4 Channel DAC and DAC Buffers



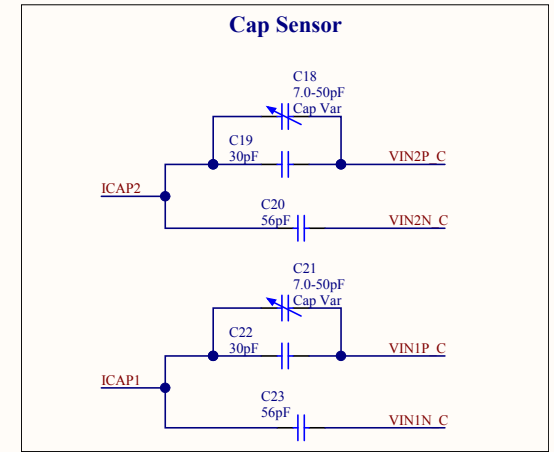
### 4 x 3PST MUX for Buffer Outputs



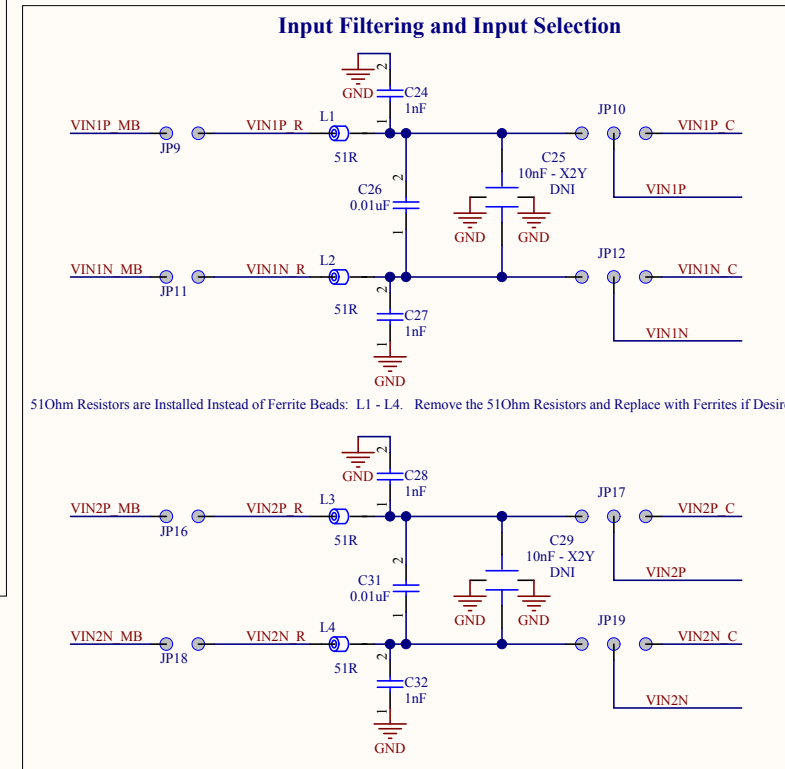
### Resistive Bridge



### Cap Sensor

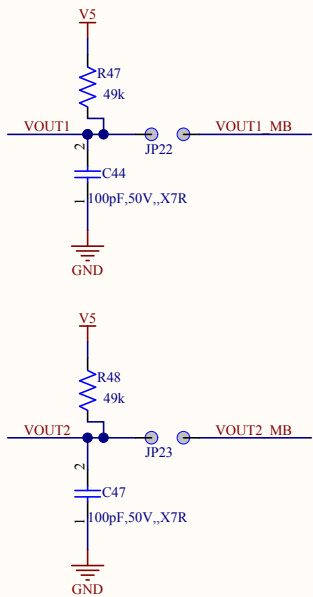


### Input Filtering and Input Selection

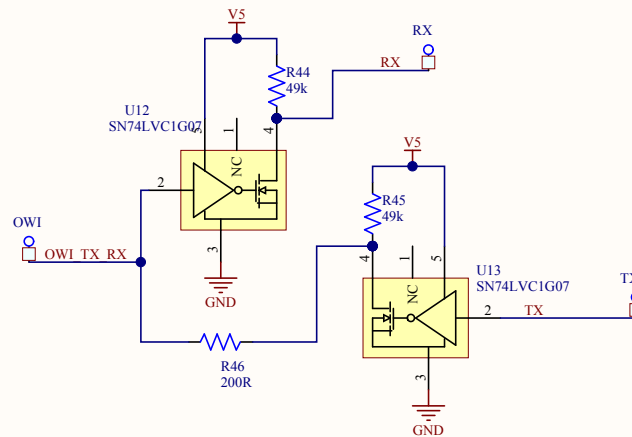


DACs / Inputs

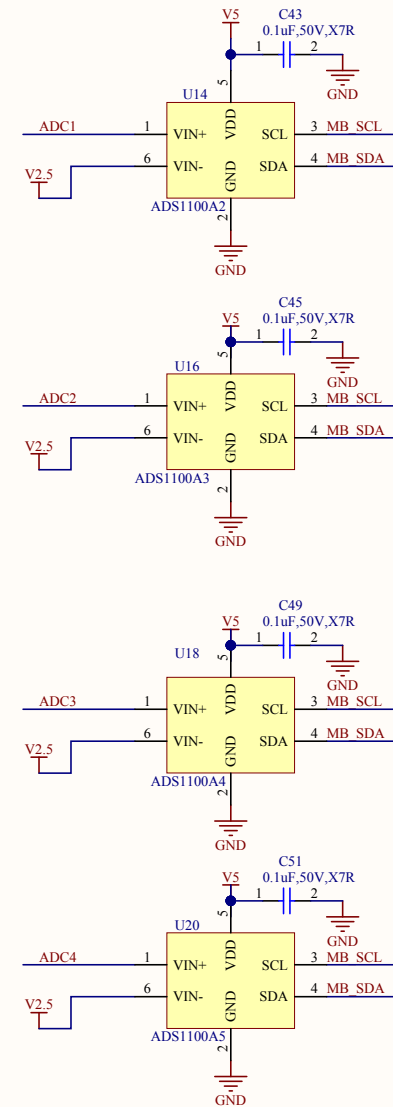
### PSSC DAC Outputs



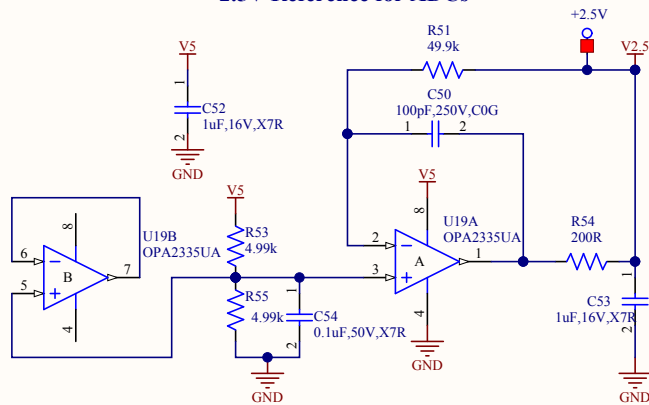
### OWI -> TX/RX



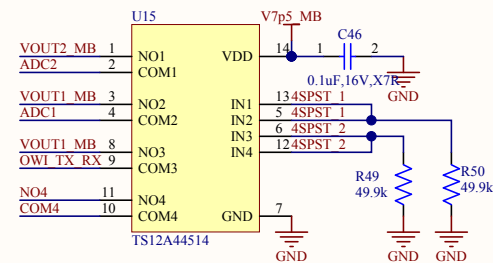
### 4 x ADC



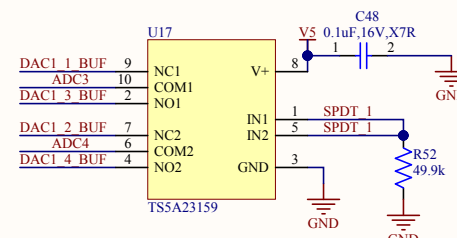
### 2.5V Reference for ADCs

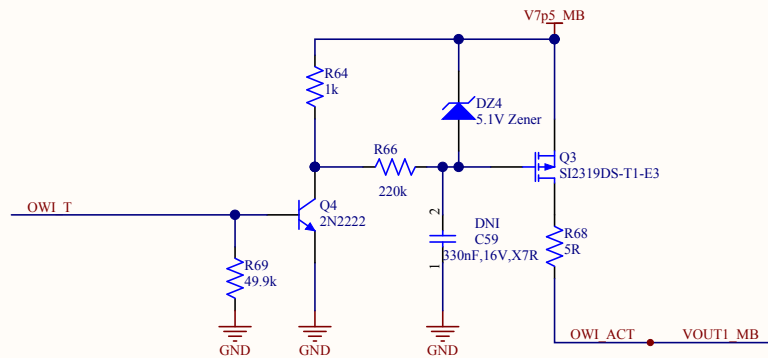


### PSSC DAC Output MUX

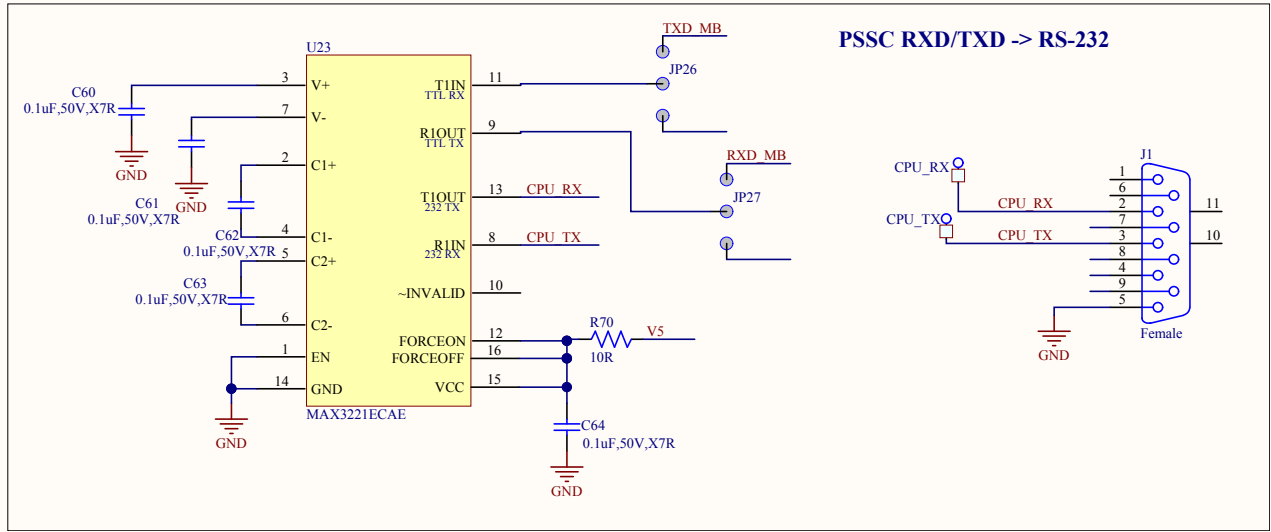


### ADC3 & ADC4 Input MUX





OWI\_Activation

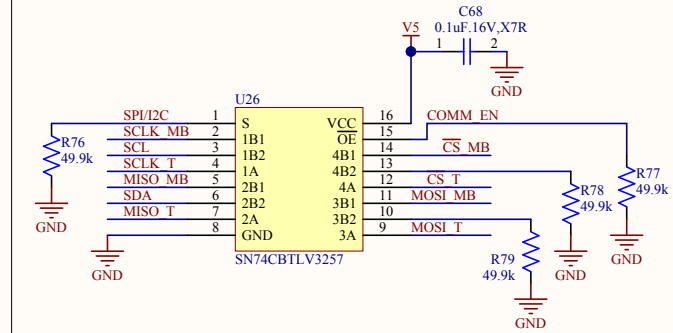


MISO_T	IO-MISO	1	MISO, SDA	2	GND
SCLK_T	IO-SCLK	3	SCLK, SCL	4	GND
/CS_T	IO-CS	5	CS (SS)	6	GND
MOSI_T	IO-MOSI	7	MOSI	8	GND
SPI/I2C	IO-11	9		10	IO-8 TX
OWI_T	IO-0	11		12	IO-1
I2C_MB/PSSC	IO-2	13		14	IO-3
3PST_2	IO-4	15		16	IO-5
SPDT_1	IO-6	17		18	IO-7
	IO-6	17		20	IO-9 RX
V 5.0_WORLD	IO-OSC	21	V_5.0V (OUT)	22	PWR-DWN
	IO-OSC	21	CHIP OSC (OUT)	24	IO-10 (SLOW OSC)
V 3.3_WORLD	V DVM_1	25	V_3.3V (OUT)	26	IO-A
	V DVM_2	27	DVM-1	28	IO-B
	V DVM_3	29	DVM-2	30	DAC OUT
			DVM-3		IO-DAC

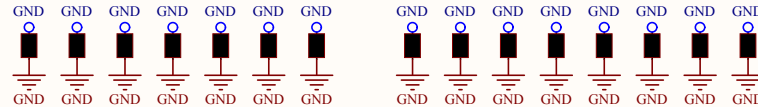
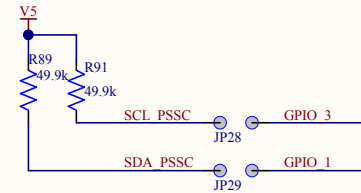
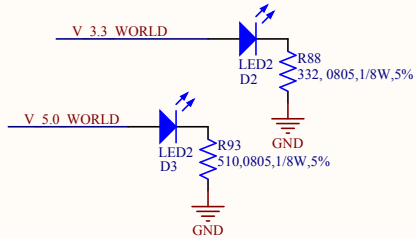
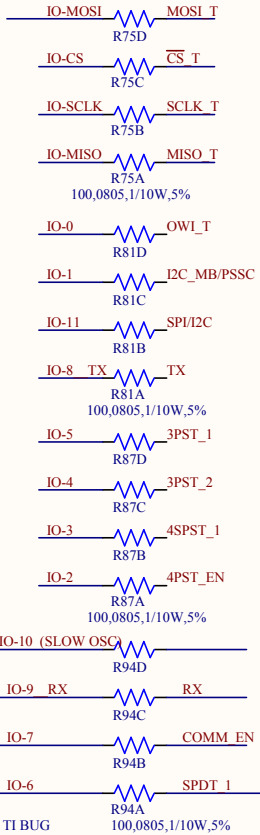
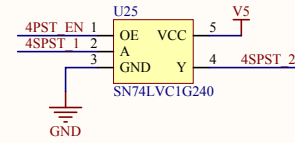
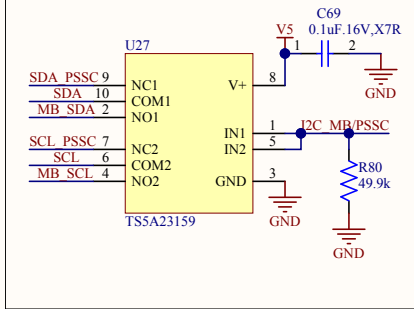
TIGER - A

TX  
4SPST\_1  
4SPST\_2  
3PST\_1  
COMM\_EN  
RX  
V3intD

### TI-GER COMM MUX - SPI/I2C



### I2C MUX - PSSC / EVM





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